

ABSTRACT

A carrier and package for plural semiconductor devices includes a member with device-conformal apertures therethrough. A first removable cover is attached to one side of the member to close one end of each aperture. After devices are inserted into the apertures with their first ends "up" and their second ends "down," a second removable cover is attached to the other side of the member to close the other end of each aperture. After inverting the assembly, removal of the first cover presents the devices in the apertures with their second ends "up" and their first ends "down."

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